ABSTRACT OF THE DISCLOSURE

LEAD FRAME

A lead frame is provided which enables a coating of an insulating adhesive for fixing a semiconductor chip to be evenly and thickly formed on inner leads. In a lead frame wherein an insulating adhesive for fixing a semiconductor chip is applied to a semiconductor chip mounting region, inner leads 1 are set to a value of w/s of not more than 1 wherein w represents the lead width and s represents the lead spacing.

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